

Highlights

Excellent Quality and Superior Service

- ▶ State-of-the-Art Fully Automatic Dicing Systems including 300 mm (12 inch) wafer diameter, dual spindle systems
- ▶ Silicon, GaAs, Sapphire, Quartz, Glass, etc.
- ▶ Bumped Wafers
- ▶ Imaging, Optical sensor and MEMS devices
- ▶ Narrow Streets
- ▶ Experts with volume DAF (die attach film) wafer dicing
- ▶ Unpassivated Wafers
- ▶ Real-time topside chipping monitor
- ▶ Sidewall and backside chipping monitor
- ▶ Wafer Backgrinding & Polishing to 50µm thickness
- ▶ Wafers with Multiple Die Types & Sizes
- ▶ Electronic Wafer Maps
- ▶ Ultra-small (.009 inch) and Large (8x8 inch) die sizes
- ▶ < Class 100 work stations
- ▶ High volume die inspection and Pick-&-Place

CORWIL will thin, saw, clean and optically inspect your wafers and die in preparation for assembly or for Die Sales shipments to your customers. Visual inspections to commercial, Mil-Std-883 (Class B or Class S), and Medical Electronics specifications. We are experts with bumped wafers, optical sensor and image devices, Low K wafers, and MEMS devices. CORWIL also specializes in dicing unique wafers like multi-die reticles, ultra-thin (25µm) and bonded wafers. Materials processed at CORWIL include Silicon, GaAs, SiGe, Sapphire, Quartz, Laminates, Glass and many other materials.

- **Wafer Dicing** - Fully Automatic World Class Disco Wafer Dicing systems handle wafers ranging from fragments or individual reticles to 12-inch (300 mm) diameter. Wafer cleanliness and ESD controlled with surfactants, CO₂ bubbler and anti-static ionized work stations. Our experienced operators can take your multiple-die type wafers with complex dicing patterns to save all die, or sacrifice some to retrieve the dice you need. Kerf widths as low as 15µm.
- **Recognized as Industry's Technical Leader** - CORWIL dicing processes are optimized for chip-free and fast turn-around dicing yielding the highest mechanical die strength.
- **Pick-&-Place** - Automatic high speed pick-&-place machines for placing dice in waffle pack or Gel Pak, or tape-and-reel. CORWIL will even reconstruct known good die (KGD) to tape and frame. Manual pick-&-place available for delicate dice sensitive to topside damage (unpassivated, MEMS, imager devices, or ultra-thin bumped wafers). Die picking from electronic wafer maps and individual die I.D tracking available. Bumped dice can be placed into waffle pack or tape-and-reel either bump side up or down.
- **Die Inspection** - 100% visual inspection (high & low power) available to the specification you need. All operators are trained and certified to commercial, MIL-STD-883, Method 2010 Cond A & B, and customer specific requirements such as those used for the medical electronics industry.
- **High Volume Inspection** - CORWIL's powerful automatic vision inspection systems inspect hundreds of thousands of dice per day. We can meet your tight time schedule to process, inspect, and pack your dice in the fastest time possible.
- **Quality and Service** - Each order is entered on a custom production traveler generated for your specific requirements allowing for flexible process flows and lot tracking.
- **High Volume, High Quality Dicing** - CORWIL processes tens of millions of dice per month and is the leading quality supplier of wafer sawing and die visual inspection services for the heart pacemaker, defibrillator, and other medical markets.
- **CORWIL** has built its reputation providing customers with:
excellent quality and superior service

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DSCC QML Listed
(Qualified Manufacturers List)
MIL-STD-883 DSCC Suitability